



PATENT
Attorney Docket No.: COOL-00700

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	Group Art Unit: 3746
Thomas W. Kenny et al.)	Examiner:
Serial No.: 10/669,495)	<u>TRANSMITTAL LETTER</u>
Filed: September 23, 2003)	162 N. Wolfe Road
For: MICRO-FABRICATED)	Sunnyvale, CA 94086
ELECTROKINETIC PUMP WITH)	(408) 530-9700
ON-FRIT ELECTRODE)	Customer No.: 28960

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

Enclosed please find an Information Disclosure Statement and Form PTO-1449, including copies of the references contained thereon, for filing in the U.S. Patent and Trademark Office.

You will also find enclosed the associated Transmittals, Electronic Information Disclosure Statements, and United States Patent and Trademark Office Acknowledgment Receipts for the electronically filed Information Disclosure Statement (EFS ID #57861); (EFS ID #57862); (EFS ID #57863); and (EFS ID #57864) filed on March 25, 2004.

The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 3-26-04

By: Thomas B. Haverstock
Thomas B. Haverstock
Reg. No.: 32,571

Attorneys for Applicants

CERTIFICATE OF MAILING (37 CFR § 1.8(a))

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HAVERSTOCK & OWENS LLP.

Date: 3-26-04 By: John D. Haverstock

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ACKNOWLEDGEMENT RECEIPT

Electronic Version 1.1

Stylesheet Version v1.1.1

Title of Invention	MICRO-FABRICATED ELECTROKINETIC PUMP WITH ON-FRIT ELECTRODE										
Submission Type:	Information Disclosure Statement										
Application Number:	10/669495	*10/669495*									
EFS ID:	57862										
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Submitted by:	Elec. Sign.	Sign. Capacity
Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney

Documents being submitted	Files
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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	1	5383340	1995-01-24	Larson et al.			
	2	5421943	1995-06-06	Tam et al.			
	3	5427174	1995-06-27	Lomolino, Sr. et al.			
	4	5436793	1995-07-25	Sanwo et al.			
	5	5459099	1995-10-17	Hsu			
	6	5508234	1996-04-16	Dusablon, Sr. et al.			
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24	5800690	1998-09-01	Chow et al.
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26	5835345	1998-11-10	Staskus et al.
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28	5858188	1999-01-12	Soane et al.
29	5863708	1999-01-26	Zanzucchi et al.
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33	5876655	1999-03-02	Fisher
34	5880017	1999-03-09	Schwlebert et al.
35	5880524	1999-03-09	Xie
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41	5965001	1999-10-12	Chow et al.
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48	6013164	2000-01-11	Paul et al.
49	6019882	2000-02-01	Paul et al.
50	6054034	2000-04-25	Soane et al.

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	1	6068752	2000-05-30	Dubrow et al.			
	2	6090251	2000-07-18	Sundberg et al.			
	3	6096656	2000-08-01	Matzke et al.			
	4	6100541	2000-08-08	Nagle et al.			
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45	6495015	2002-12-17	Schoeniger et al.	B1
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47	6543521	2003-04-08	Sato et al.	B1
48	6553253	2003-04-22	Chang	B1
49	6572749	2003-06-03	Paul et al.	B1
50	6588498	2003-07-08	Reysin et al.	B1

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or 20020011330 or 20020134543).pn.

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	1	6591625	2003-07-15	Simon	B1		
	2	6632655	2003-10-14	Mehta et al.	B1		

US Published Applications

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	1	20010016985	2001-08-30	Insley et al.	A1		
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	5	20010046703	2001-11-29	Burns et al.	A1		
	6	20010055714	2001-12-27	Cettour-Rose et al.	A1		

	7	20020011330	2002-01-31	Insley et al.	A1
	8	20020134543	2002-09-26	Estes et al.	A1

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Stylesheet Version v1.1.1

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Submission Type:	Information Disclosure Statement										
Application Number:	10/669495	*10/669495*									
EFS ID:	57861										
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First Named Applicant:	Thomas Kenny										
Attorney Docket Number:											
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Page 2 of 2

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TRANSMITTAL							
Electronic Version v1.1 Stylesheet Version v1.1.0							
Title of Invention	MICRO-FABRICATED ELECTROKINETIC PUMP WITH ON-FRIT ELECTRODE						
Application Number:	10/669495 *10/669495*						
Date:	2003-09-23						
First Named Applicant:	Thomas W. Kenny						
Confirmation Number:	3987						
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Thomas B. Haverstock Registered Number: 32571</td><td>/tbh/</td><td>Attorney</td></tr></tbody></table>		Submitted by:	Elec. Sign.	Sign. Capacity	Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney
Submitted by:	Elec. Sign.	Sign. Capacity					
Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney					

Documents being submitted	Files
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8
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Title of Invention	MICRO-FABRICATED ELECTROKINETIC PUMP WITH ON-FRIT ELECTRODE
Application Number:	10/669495
Confirmation Number:	3987
First Named Applicant:	Thomas Kenney
Attorney Docket Number:	
Search string:	(3654988 or 3817321 or 3823572 or 3923426 or 3929154 or 4109707 or 4194559 or 4248295 or 4138996 or 4312012 or 4540115 or 4450472 or 4485429 or 4516632 or 4561040 or 4567505 or 4573067 or 4664181 or 4758926 or 4866570 or 4868712 or 4894709 or 4896719 or 4908112 or 4938280 or 5009760 or 5016138 or 5057908 or 5058627 or 5070040 or 5083194 or 5088005 or 5096388 or 5099311 or 5099910 or 5125451 or 5131233 or 5203401 or 5218515 or 5219278 or 5232047 or 5239200 or 5263251 or 5274920 or 5308429 or 5309319 or 5317805 or 5325265 or 5336062 or 5380956).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Information Disclosure Statement

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Signature

Examiner Name	Date

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PATENT
Attorney Docket No.: COOL-00700

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	Group Art Unit: 3746
Thomas W. Kenny et al.)	Examiner:
Serial No.: 10/669,495)	
Filed: September 23, 2003)	<u>SUPPLEMENTAL INFORMATION</u>
For: MICRO-FABRICATED)	<u>DISCLOSURE STATEMENT</u>
ELECTROKINETIC PUMP WITH)	
ON-FRIT ELECTRODE)	162 N. Wolfe Road
)	Sunnyvale, CA 94086
)	(408) 530-9700

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #57861); (EFS ID #57862); (EFS ID #57863); and (EFS ID #57864). Applicants have become aware of the following printed publication which may be material to the examination of this application:

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Respectfully submitted,
HAVERSTOCK & OWENS LLP

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